

# TRANSMITTAL FORM

Application Number	09/786,597
Filing Date	February 28, 2001
First Named Inventor	Kenichi HIRAHARA
Title	Through Hole Conduction Structure of Flexible Multilayer Circuit Board and Forming Method Thereof
Group Art Unit	2827
Examiner Name	Tuan T. DINH
Attorney Docket Number	KAM/133/PC/US

## ENCLOSURES

TO: Commissioner For Patents  
Washington, DC 20231

- |   |  |
|---|--|
| <input checked="" type="checkbox"/> RESPONSE TO OFFICE ACTION | <input type="checkbox"/> Preliminary Amendment                     |
| <input type="checkbox"/> Information Disclosure Statement     | <input checked="" type="checkbox"/> Postcard Reflecting Enclosures |
| <input type="checkbox"/> Other:                               |  |

☒ It is hereby petitioned that any required extension of time be granted for filing the Amendment. An extension of -0- month(s) having a fee of \$ -0- appears required.

☒ A check in the amount of \$ -0- is attached. Please credit any overpayment to Deposit Account 16-2563 of Alix, Yale & Ristas, LLP.

The Commissioner is hereby requested and authorized to charge Deposit Account 16-2563 of Alix, Yale & Ristas, LLP for any fee, not enclosed herewith, due for any reason in connection with the amendment or this or any other document accompanying the amendment, including (a) any filing fees under 37 CFR 1.16 for the presentation of extra claims and (b) any patent application processing fees under 37 CFR 1.17. ☒ **A duplicate copy of this sheet is attached.**

## SIGNATURE OF APPLICANT, ATTORNEY OR AGENT

Firm or Individual name Guy D. Yale  
Signature [Signature]  
Date 1-31-2003

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## CERTIFICATE OF MAILING

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Typed or Printed Name <u>Guy D. Yale</u>	Reg. No. <u>29,125</u>
Signature <u>[Signature]</u>	Date: <u>1-31-2003</u>



ATTORNEY DOCKET NO. KAM/133/PC/US

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Kenichi HIRAHARA et al

Application Number: 09/786,597

Group/Art Unit 2827

Filed: February 28, 2001

Examiner: Tuan T. DINH

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Title: Through Hole Conduction Structure of Flexible  
Multilayer Circuit Board and Forming Method  
Thereof

Commissioner for Patents  
United States Patent and Trademark Office  
Washington, DC 20231

Sir:

### RESPONSE TO OFFICE ACTION

In response to the Office Action dated November 13, 2002, Applicant respectfully requests entry and consideration of the following Amendment and Remarks and reconsideration and allowance of all claims.

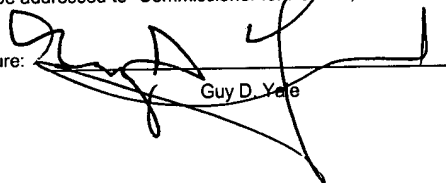
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Reg. No.: 29,125

Date: January 31, 2003